

ABSTRACT

In a method for polishing a surface of a semiconductor wafer, a first polishing process using slurry is performed
5 on a surface of the insulator layer after an insulator layer is deposited on the semiconductor wafer. Subsequently, a second polishing process using water instead of the slurry is performed on the surface of the insulator layer. As a result, the production cost is decreased and many defects
10 resulting from the scratches are prevented.

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